

Specification for Approval

Customer:

Customer Part No.:

Supplier: Fuda Semiconductor (Hefei) Co., Ltd.

Spec description:

Supplier Part No.: J-FDIMPP

Date: 2023/6/1

Version: A.0

Draw:

Supplier Approve		Customer Approve
EE Confirm by	PE Confirm by	
QE Confirm by	Approval by	

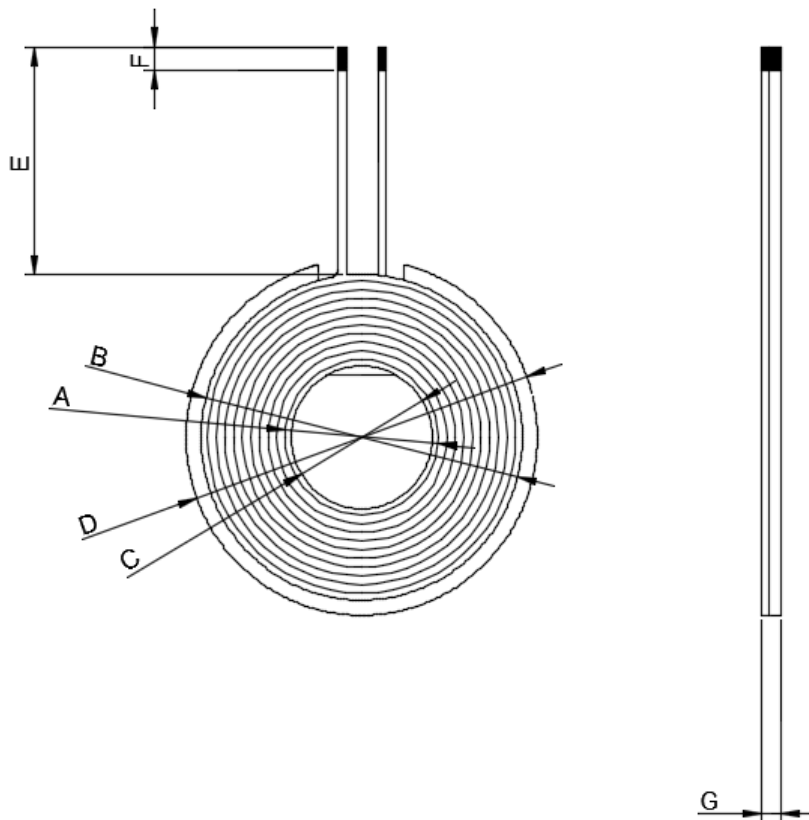
Version Change History

Revision	Before change	After change	Date	Approval by
A.0	—	Initial Release	2023/6/1	

1. Manufacturer information

Items	Manufacturer name	Approval
The first resource	Fuda Semiconductor (Hefei) Co., Ltd.	Luo jie
The second resource		

2. Dimension specification



Unit: mm

A	B	C	D	E	F	G
20.5±0.5	39±1	19.5±0.3	42.5±0.5	8±1	4±1.5	2.05±0.1

Note:

- No high-temperature adhesive tape is applied at the coil leads.
- When the coil is in contact with the magnetic shield, it must not protrude beyond the edge of the magnetic shield.

3. Schematic diagram



4. Electronic character

TEMPERATURE: $25 \pm 10^{\circ}\text{C}$, RELATIVE HUMIDITY : $65 \pm 20\%$

TIEM	SPECIFICATION	TEST FREQUENCY	TEST EQUIPMENTS
IND	$8.4\text{UH} \pm 10\%$	100 KHZ/1.0V	LCRMETRTH2830N
DCR	50m Ω Max	\	PH2511S
Q	$100 \pm 10\%$	100 KHZ/1.0V	LCRMETRTH2830N

5. Coil specification

Turns	Wire Dia.	Wdg. Type Spred/Close	Wdg.Direction	Intersect Yes/Not	Coil Positive/ Anti Paste
11T S	0.08*80P (Silk-Covered Wire)	(Close)	(Anticlockwise)	(Yes)	(Anti-/Paste)

6. Bill of materials

number	Material name	Description	Material Code
1	wire rod	0.08 * 80P Hot air twisted wire	JX-2U-F-0025
2	Hard magnetic sheet	G42.5*19.5*2.0H	
3	Adhesive	JS-E103 (Thickened) White Adhesive	
4			
5			
6			
7			